

## MOSFET Silicon N-Channel MOS

### 1. Applications

Single-ended flyback.

PD Adaptor,LCD & PDP TV and LED lighting.



### 2. Features

Low drain-source on-resistance:  $R_{DS(ON)} = 0.870\Omega$  (typ.)

Easy to control Gate switching

Enhancement mode:  $V_{th} = 2.8$  to  $4.2$  V

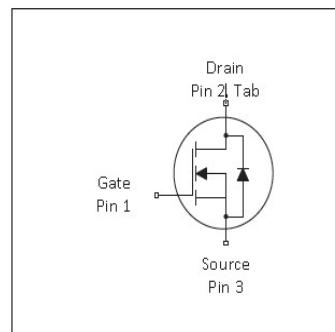
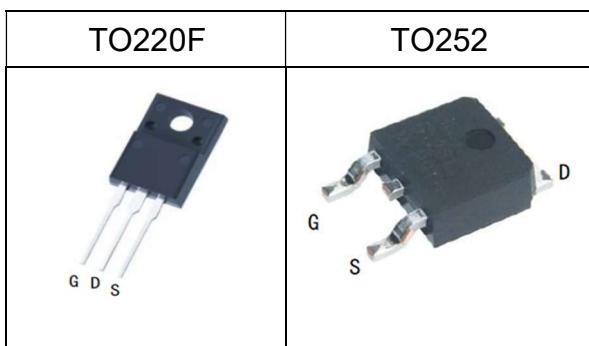


**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS}$ @ $T_{j,max}$	750	V
$R_{DS(on),max}$	950	$m\Omega$
$Q_{g,typ}$	10.3	nC
$I_{D,pulse}$	18	A

### 3. Packaging and Internal Circuit

Part Name	Package	Marking
ASA70R950E	TO220F	ASA70R950E
ASD70R950E	TO252	ASD70R950E



## 1 Maximumratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximumratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$		-	6	A	$T_c=25^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,\text{pulse}}$	-	-	18	A	$T_c=25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	180	mJ	$T_c=25^\circ\text{C}, VDD=50\text{V}, L = 10\text{mH}, RG=25\Omega$
Avalanche current, single pulse	$I_{AS}$	-	-	6	A	$T_c=25^\circ\text{C}, VDD=50\text{V}, L = 10\text{mH}, RG=25\Omega$
MOSFET dv/dt ruggedness	dv/dt	-	-	36	V/ns	$V_{DS}=0...400\text{V}$
Gate source voltage (static)	$V_{GS}$	-20	-	20	V	static;
Gate source voltage (dynamic)	$V_{GS}$	-30	-	30	V	AC ( $f > 1 \text{ Hz}$ )
Power dissipation (TO220F)	$P_{tot}$	-	-	26	W	$T_c=25^\circ\text{C}$
Power dissipation (TO252)	$P_{tot}$	-	-	37	W	$T_c=25^\circ\text{C}$
Storage temperature	$T_{stg}$	-55	-	150	$^\circ\text{C}$	
Operating junction temperature	$T_j$	-55	-	150	$^\circ\text{C}$	
Continuous diode forward current	$I_S$	-	-	48	A	$T_c=25^\circ\text{C}$
Reverse diode dv/dt <sup>3)</sup>	dv/dt	-	-	15	V/ns	$V_{DS}=0...400\text{V}, I_{SD} \leq 48\text{A}, T_j=25^\circ\text{C}$ see table 8

<sup>1)</sup>Limited by  $T_{j,\text{max}}$ . Maximum Duty Cycle D = 0.50

<sup>2)</sup>Pulse width  $t_p$  limited by  $T_{j,\text{max}}$

<sup>3)</sup>Identical low side and high side switch with identical  $R_G$

## 2 Thermalcharacteristics

**Table 3 Thermalcharacteristics (T0220 FullPAK)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	4.9	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	80	°C/W	device on PCB, minimal footprint

**Thermalcharacteristics (T0252)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	3.41	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	62	°C/W	device on PCB, minimal footprint

### 3 Electrical characteristics

at  $T_j=25^\circ\text{C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	705	-	-	V	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=10\text{mA}$
Gate threshold voltage	$V_{(\text{GS})\text{th}}$	2.8		4.2	V	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$
Zero gate voltage drain current	$I_{\text{DSS}}$	-	-	1	$\mu\text{A}$	$V_{\text{DS}}=700\text{V}, V_{\text{GS}}=0\text{V}, T_j=25^\circ\text{C}$
Gate-source leakage current	$I_{\text{GSS}}$	-	-	100	nA	$V_{\text{GS}}=30\text{V}, V_{\text{DS}}=0\text{V}$
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	-	0.87	0.95	$\Omega$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=2\text{A}, T_j=25^\circ\text{C}$
Gate resistance (Intrinsic)	$R_{\text{G}}$	-	32	-		$f=1\text{MHz}$ , open drain

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{\text{iss}}$	-	377	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Output capacitance	$C_{\text{oss}}$	-	33	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Reverse transfer capacitance	$C_{\text{rss}}$	-	4.55	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Turn-on delay time	$t_{\text{d}(\text{on})}$	-	8.4	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=2.5\text{A}, R_{\text{G}}=6.8\Omega$ ; see table 9
Rise time	$t_{\text{r}}$	-	21.6	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=2.5\text{A}, R_{\text{G}}=6.8\Omega$ ; see table 9
Turn-off delay time	$t_{\text{d}(\text{off})}$	-	45.2	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=2.5\text{A}, R_{\text{G}}=6.8\Omega$ ; see table 9
Fall time	$t_{\text{f}}$	-	24.4	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=2.5\text{A}, R_{\text{G}}=6.8\Omega$ ; see table 9

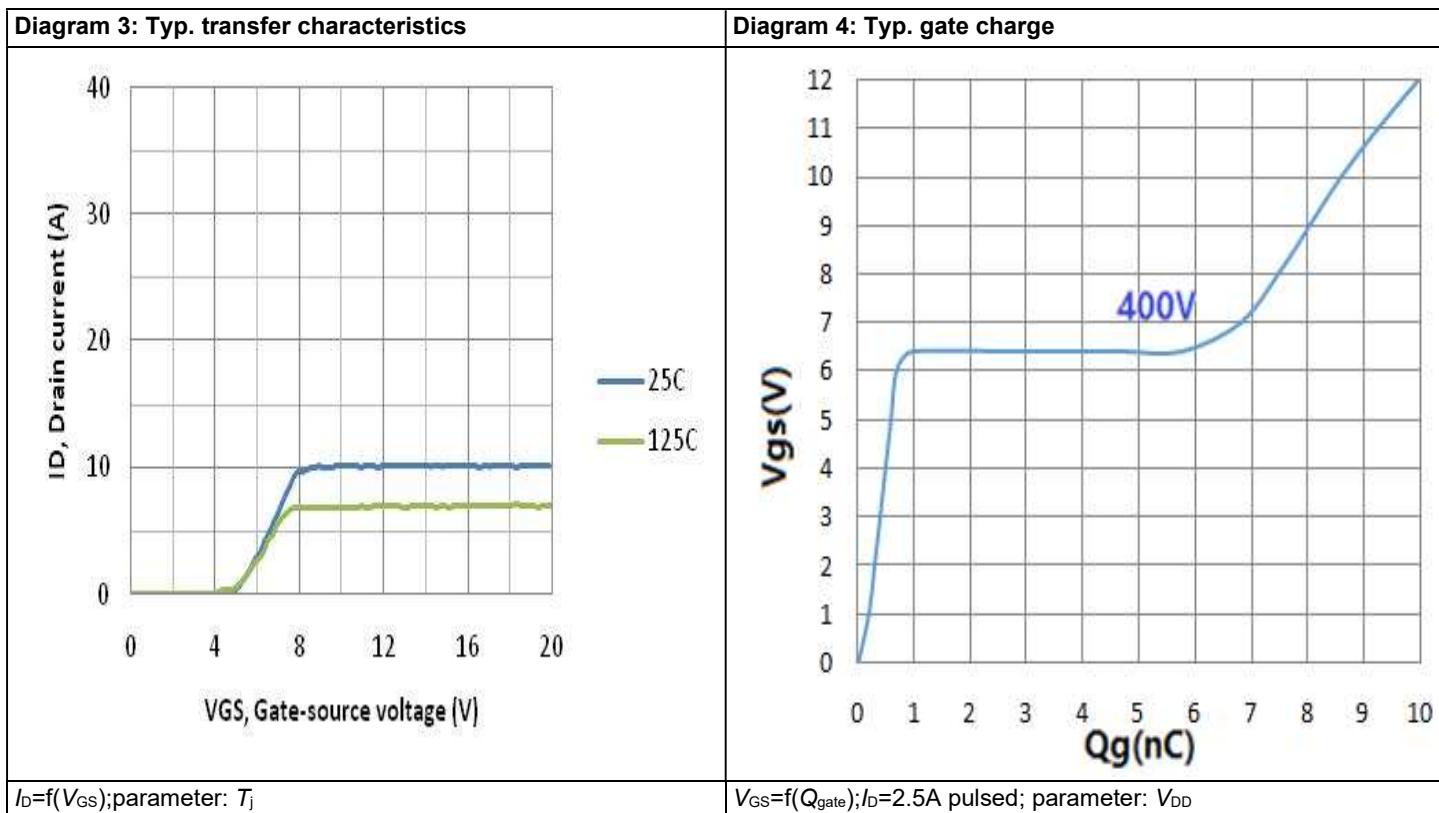
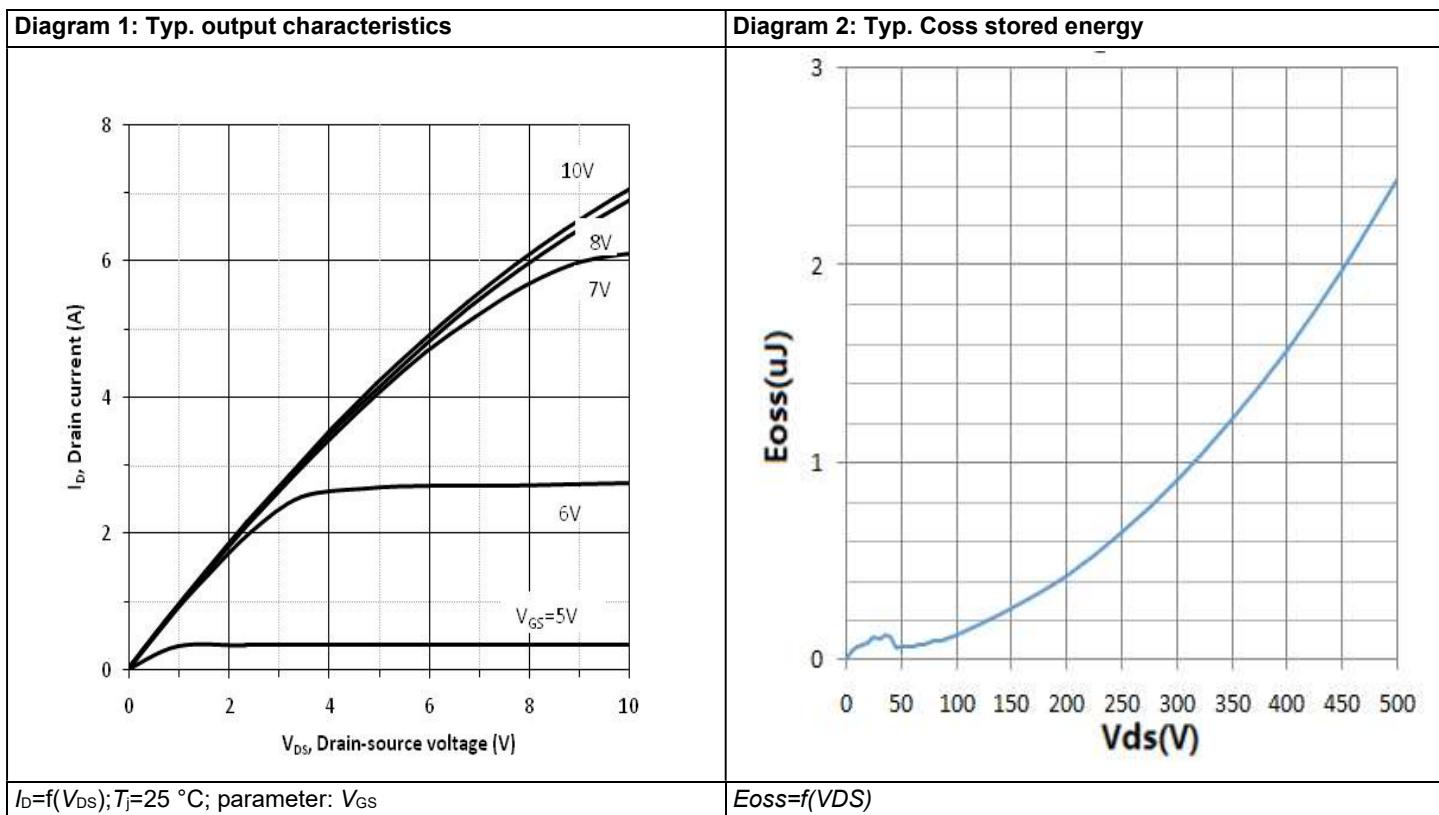
**Table 6 Gate charge characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{\text{gs}}$	-	1.845	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=2.5\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate to drain charge	$Q_{\text{gd}}$	-	2.723	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=2.5\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate charge total	$Q_{\text{g}}$	-	10.3	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=2.5\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate plateau voltage	$V_{\text{plateau}}$	-	6.4	-	V	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=2.5\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$

**Table 7 Reverse diode characteristics**

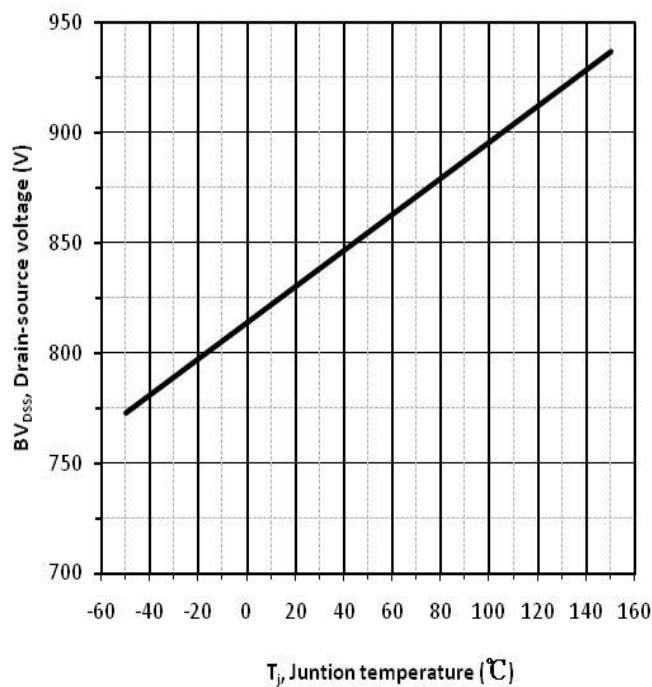
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$	-	0.77	-	V	$V_{GS}=0V$ , $I_F=1A$ , $T_j=25^\circ C$
Reverse recovery time	$t_{rr}$	-	124	-	ns	$V_R=400V$ , $I_F=2.5 A$ , $di_F/dt=100A/\mu s$ ; see table 8
Reverse recovery charge	$Q_{rr}$	-	0.88	-	uC	$V_R=400V$ , $I_F=2.5 A$ , $di_F/dt=100A/\mu s$ ; see table 8
Peak reverse recovery current	$I_{rrm}$	-	10	-	A	$V_R=400V$ , $I_F=2.5 A$ , $di_F/dt=100A/\mu s$ ; see table 8

## 4 Electrical characteristics diagram

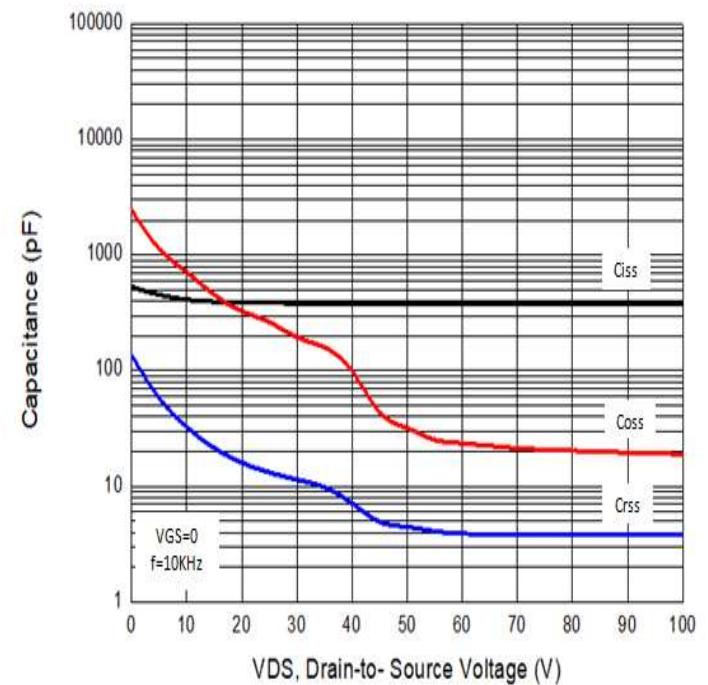


# ASA70R950E, ASD70R950E

**Diagram 5: Drain-source breakdown voltage**



**Diagram 6: Typ. capacitances**

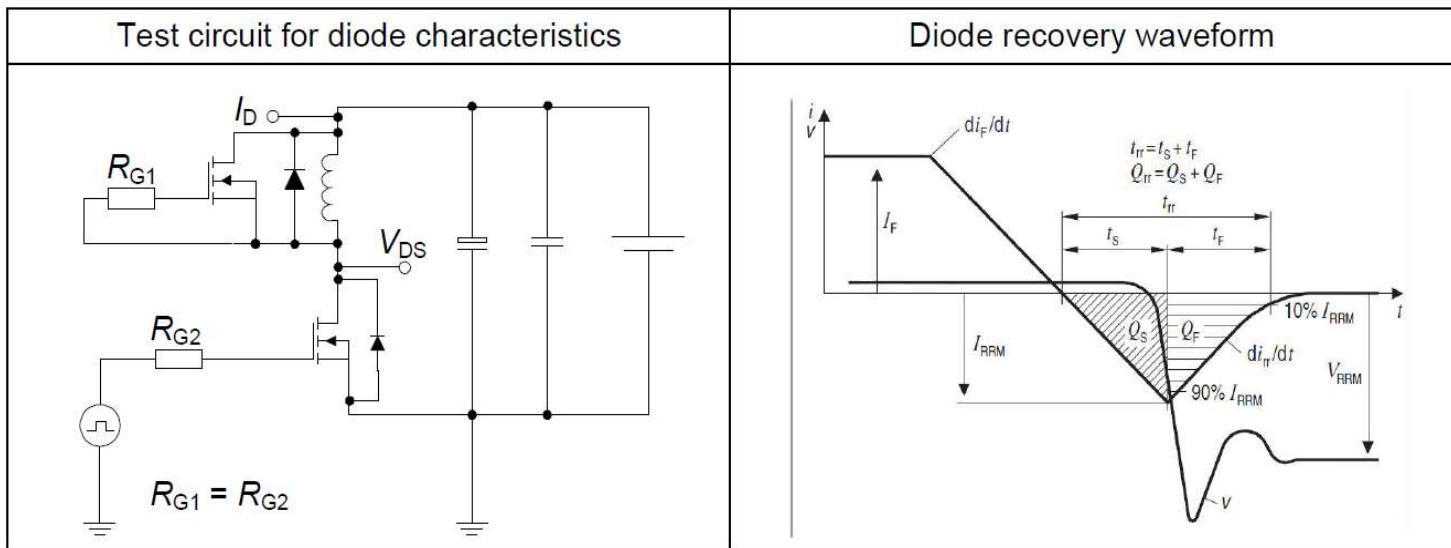


$V_{BR(DSS)} = f(T_j); I_D = 10\text{mA}$

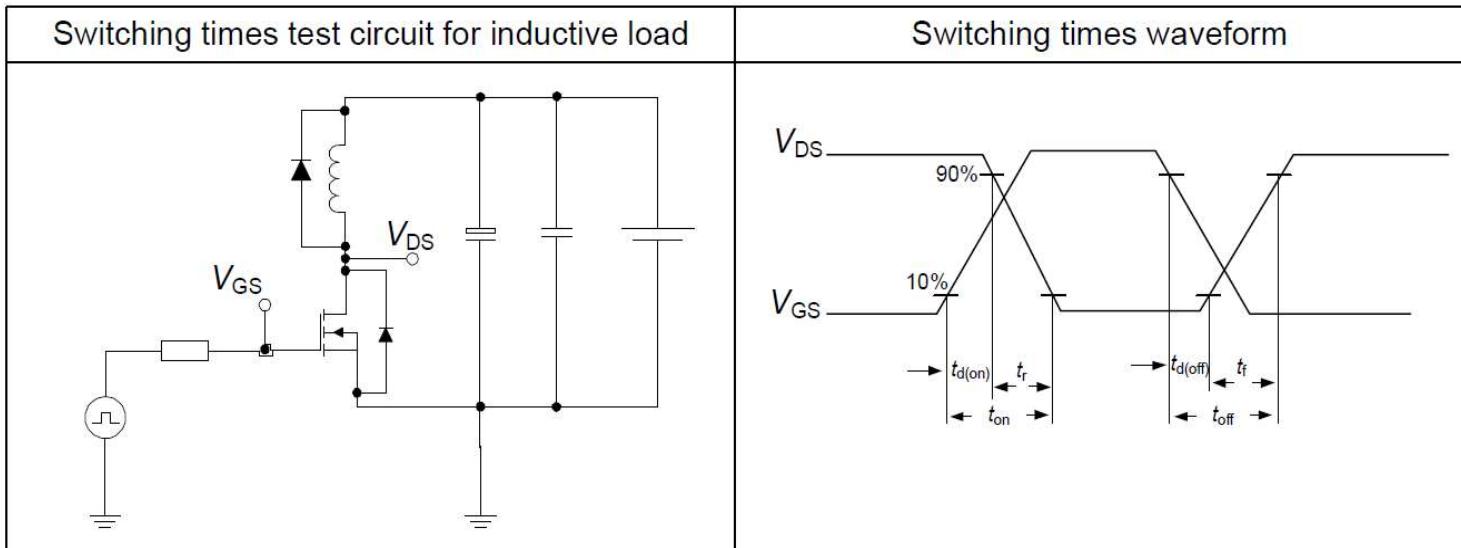
$C = f(V_{DS}); V_{GS} = 0\text{V}; f = 10\text{ kHz}$

## 5 Test Circuits

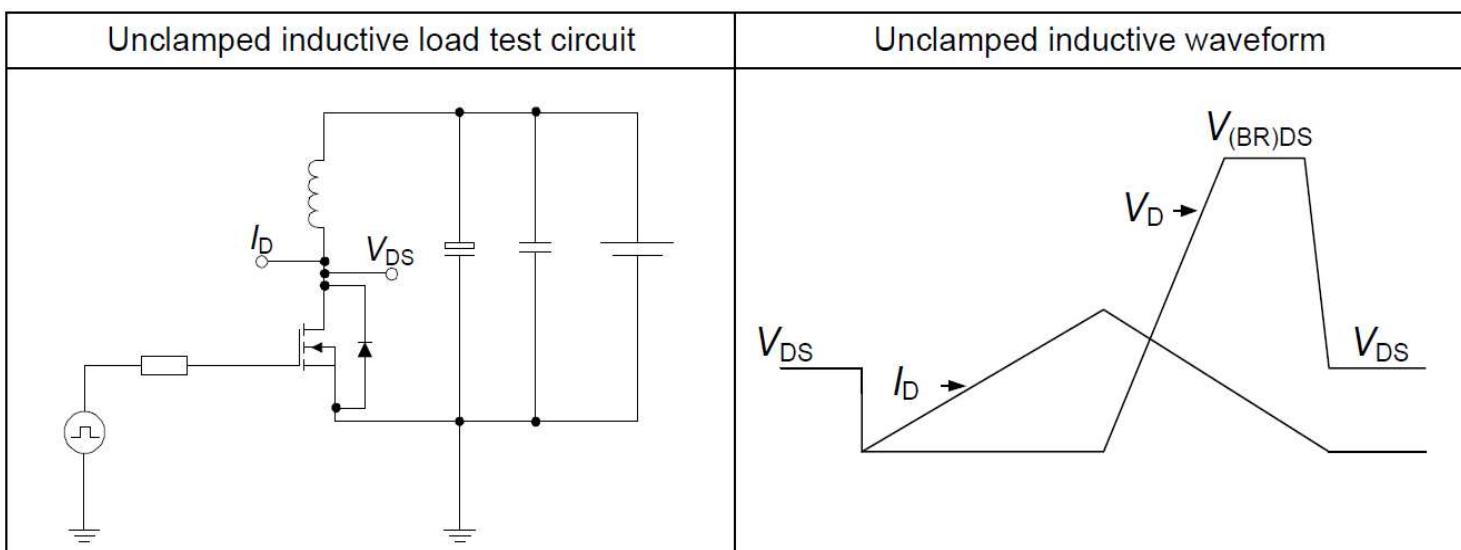
**Table 8 Diode characteristics**



**Table 9 Switching times**



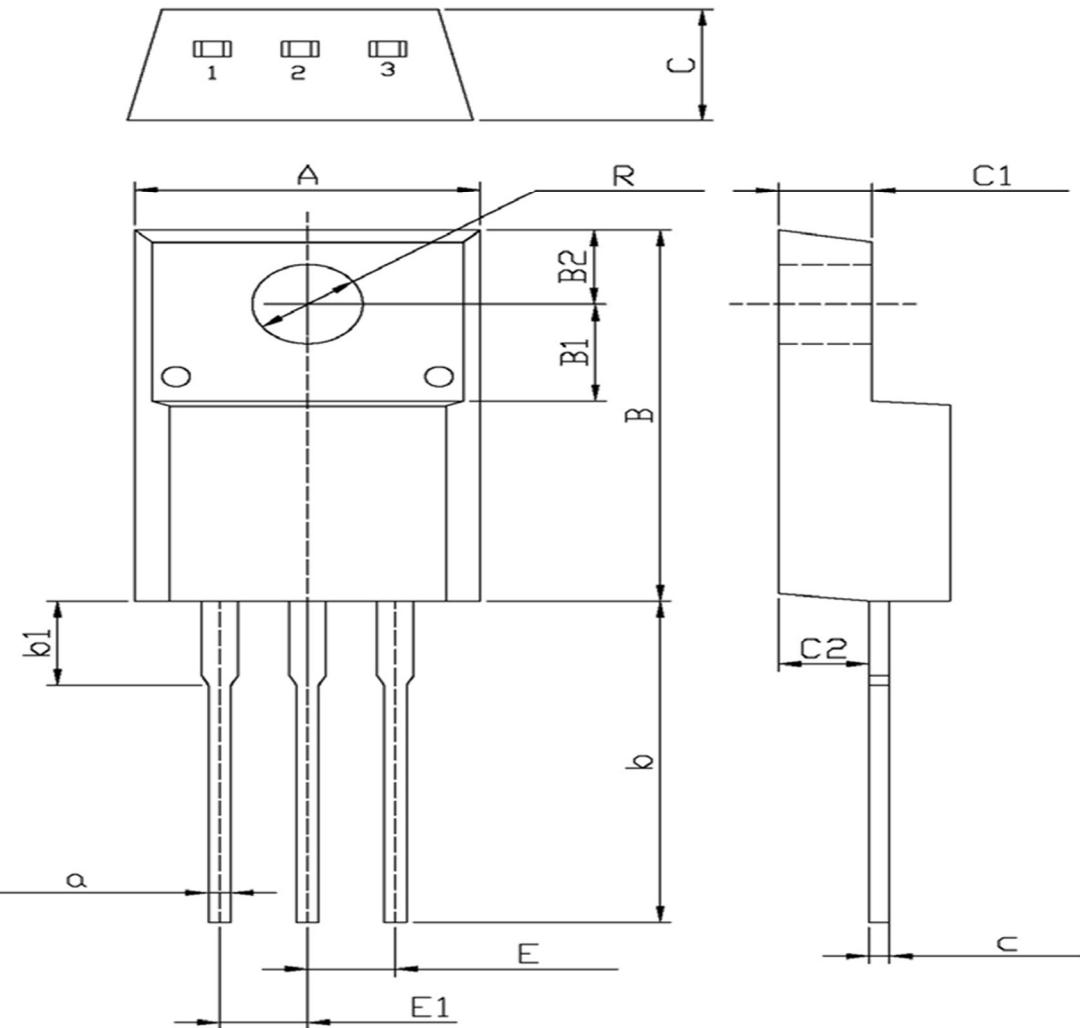
**Table10 Unclamped inductive load**



## 6 Package Outlines

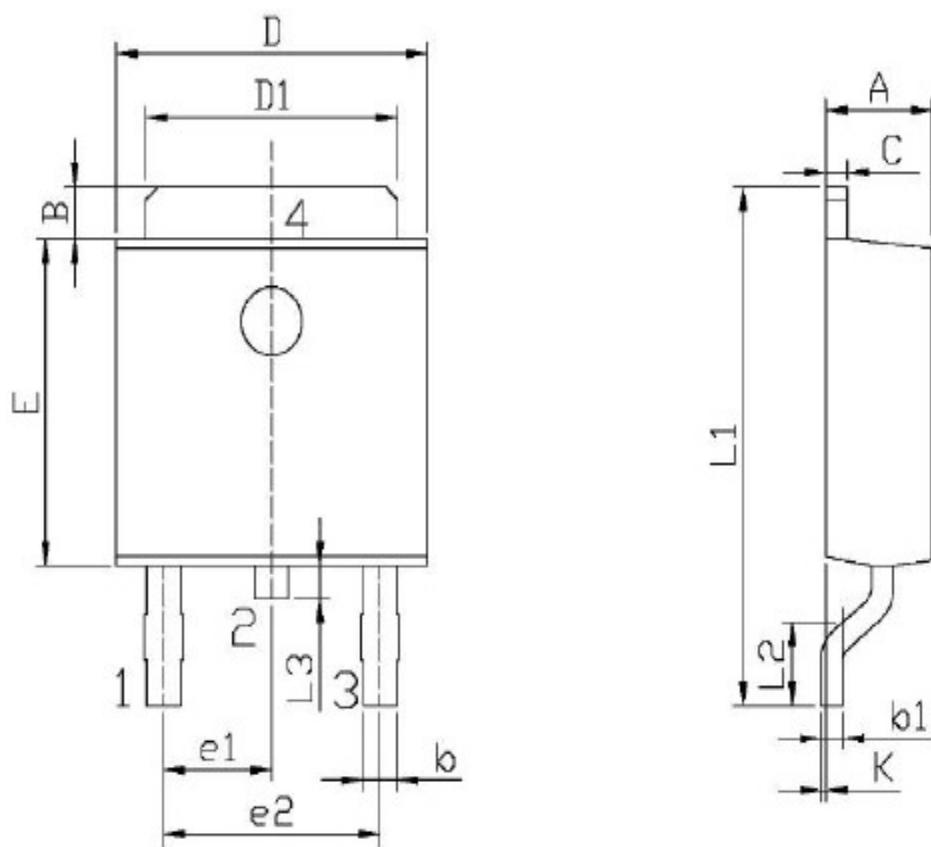
T□-220F

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
C	4.3	4.8	b1	2.9	3.9
A	9.7	10.3	a	0.55	0.9
B	14.7	16.1	E	2.29	2.79
B1	3.8	4	E1	2.29	2.79
B2	2.9	3.55	C1	2.5	2.9
R	3	3.4	C2	2.15	2.7
b	12.5	13.6	c	0.4	0.7

Figure3: Outline PG-T0220F



单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.50	0.70	e2	4.43	4.73
b1	0.45	0.55	L1	9.45	9.95
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

Figure4: Outline PG-T0252

**Revision History**

Revision	Date	Subjects (major changes since last revision)
0.1	2019-07-15	Preliminary version
1.0	2019-11-07	Fine tune outline and add Crss test data.etc
1.1	2020-03-27	Add Electrical characteristics Curve
1.2	2020-04-18	Add avalanche energy test condition, avalanche current data and test condition